

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 08/26/2022

Details for "UC2842D"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
UC2842D	NIPDAU	Level-1-260C-UNLIM	TI AGUASCALIENTES	D   14	3.91X8.65X1.58	129.1

**\*Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.048546	99.99794	999979	0.037597	376
Precious Metals	Silver	7440-22-4	0.000001	0.00206	21	0.000001	0
Sub-Total			0.048547	100	1000000	0.037597	376
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.0474	79	790000	0.036709	367
Thermoplastics	Epoxy	85954-11-6	0.0126	21	210000	0.009758	98
Sub-Total			0.06	100	1000000	0.046467	465
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	46.301585	97.049999	970500	35.858358	358584
Copper and Its Alloys	Iron	7439-89-6	1.240434	2.6	26000	0.960657	9607
Copper and Its Alloys	Phosphorus	7723-14-0	0.071564	0.150001	1500	0.055423	554
Zinc and Its Alloys	Zinc	7440-66-6	0.095418	0.2	2000	0.073897	739
Sub-Total			47.709001	100	1000000	36.948335	369483
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.157899	95.11988	951199	0.122285	1223
Precious Metals	Gold	7440-57-5	0.001295	0.78012	7801	0.001003	10
Precious Metals	Palladium	7440-05-3	0.006806	4.1	41000	0.005271	53
Sub-Total			0.166	100	1000000	0.128559	1286
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	61.256001	76	760000	47.439837	474398
Other Organic Materials	Carbon Black	1333-86-4	0.2418	0.3	3000	0.187263	1873
Thermoplastics	Epoxy	85954-11-6	16.2812	20.2	202000	12.609009	126090
Thermoplastics	Proprietary Non Halide Flame Retardant		2.821	3.5	35000	2.184729	21847
Sub-Total			80.600001	100	1000000	62.420838	624208
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.54	100	1000000	0.418204	4182
Sub-Total			0.54	100	1000000	0.418204	4182
<b>Total</b>			129.123549			100	1000000

**Important Note**

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. [See Glossary of Terms for more details.](#)

**Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and such information may not be available for release by TI. The material content information is provided by TI "as is." [For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide [Sb2O3] contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.